# SFH 3400

Smart DIL

Silicon NPN Phototransistor





# Applications

- Electronic Equipment

 Industrial Automation (Machine Controls, Light Barriers, Vision Controls)

### **Features:**

- Package: clear epoxy
- Qualifications: AEC-Q102 Qualified
- ESD: 2 kV acc. to ANSI/ESDA/JEDEC JS-001 (HBM, Class 2)
- High linearity
- Smart-DIL package
- Available only on tape and reel

### **Ordering Information**

Туре	Photocurrent <sup>1)</sup> $V_{CE} = 5 \text{ V}; \lambda = 950 \text{ nm}; E_e = 0.1 \text{ mW/cm}^2$ $I_{PCE}$	Ordering Code
SFH 3400-Z	71 280 µA	Q65110A2629
SFH 3400-2/3-Z	112 280 μA	Q65110A2634



# Maximum Ratings

T <sub>A</sub> = 25 °C			
Parameter	Symbol		Values
Operating temperature	T <sub>op</sub>	min.	-40 °C
		max.	100 °C
Storage temperature	T <sub>stg</sub>	min.	-40 °C
	5	max.	100 °C
Collector-emitter voltage	V <sub>CE</sub>	max.	20 V
Collector-emitter voltage pulse	$V_{CE \ pulse}$	max.	70 V
t ≤ 10 µs; T <sub>A</sub> = 25 °C			
Collector current	Ι <sub>c</sub>	max.	50 mA
Collector surge current	I <sub>cs</sub>	max.	100 mA
τ ≤ 10 μs			
Emitter-collector voltage	V <sub>EC</sub>	max.	7 V
Total power dissipation	P <sub>tot</sub>	max.	120 mW
ESD withstand voltage	V <sub>ESD</sub>	max.	2 kV
acc. to ANSI/ESDA/JEDEC JS-001 (HBM, Class 2)			

### **Characteristics**

T <sub>A</sub> = 25 °C				
Parameter	Symbol		Values	
Wavelength of max sensitivity	$\lambda_{_{Smax}}$	typ.	850 nm	
Spectral range of sensitivity	$\lambda_{10\%}$	typ.	460 1080 nm	
Dimensions of chip area	L×W	typ.	1 x 1 mm x mm	
Radiant sensitive area	А	typ.	0.55 mm²	
Half angle	φ	typ.	60 °	
Photocurrent V <sub>CE</sub> = 5 V; Std. Light A; $E_v$ = 1000 lx	I <sub>PCE</sub>	typ.	2600 µA	
Dark current V <sub>CE</sub> = 5 V	I <sub>CE0</sub>	typ. max.	3 nA 100 nA	
Rise time I <sub>c</sub> = 1 mA; λ = 0 nm; V <sub>cc</sub> = 5 V; R <sub>L</sub> = 1 kΩ	t <sub>r</sub>	typ.	24 µs	
Fall time $I_c = 1 \text{ mA}; \lambda = 0 \text{ nm}; V_{cc} = 5 \text{ V}; R_L = 1 \text{ k}\Omega$	t <sub>r</sub>	typ.	24 µs	
Collector-emitter saturation voltage <sup>2)</sup> $I_{c} = I_{PCE,min} \times 0.3; E_{e} = 0.1 \text{ mW/cm}^{2}; E_{v} = 0 \text{ lx}; 0$	$V_{CEsat}$	typ.	170 mV	
Capacitance V <sub>cE</sub> = 5 V; f = 1 MHz; E = 0	C <sub>CE</sub>	typ.	10 pF	
Thermal resistance junction ambient real	R <sub>thJA</sub>	max.	450 K / W	

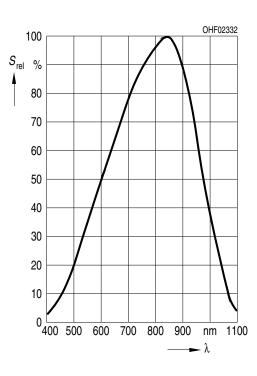


### **Photocurrent Groups**

T <sub>A</sub> = 25 °C		
Group	Photocurrent <sup>1)</sup> V <sub>CE</sub> = 5 V; $\lambda$ = 950 nm; E <sub>e</sub> = 0.1 mW/cm <sup>2</sup> min. I <sub>PCE</sub>	Photocurrent <sup>1)</sup> $V_{CE} = 5 \text{ V}; \lambda = 950 \text{ nm}; E_e = 0.1 \text{ mW/cm}^2$ max. $I_{PCE}$
1	71 µA	112 µA
2	112 µA	180 µA
3	180 µA	280 µA

# **Relative Spectral Sensitivity** <sup>3), 4)</sup>

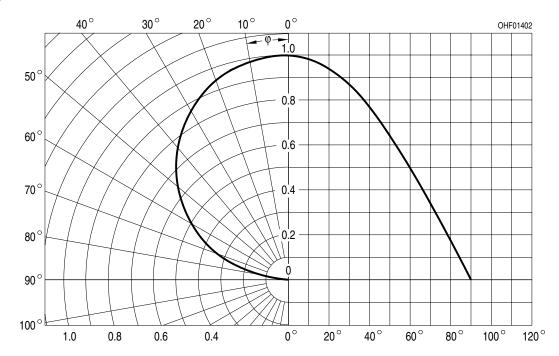
 $S_{rel} = f(\lambda)$ 





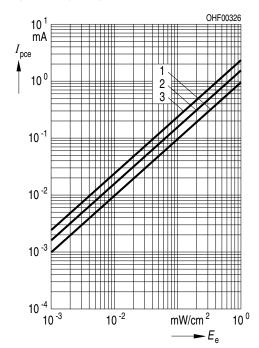
#### **Directional Characteristics** <sup>3), 4)</sup>

 $S_{rel} = f(\phi)$ 



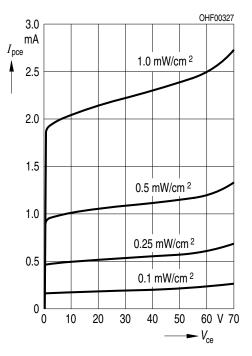
### Photocurrent <sup>3), 4)</sup>

 $I_{_{\mathrm{PCE}}} = f(E_{_{\mathrm{e}}}) ; V_{_{\mathrm{CE}}} = 5 \text{ V}$ 



### Photocurrent <sup>3), 4)</sup>

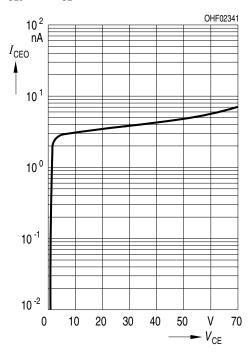
 $I_{PCE} = f(V_{CE}); E_{e} = Parameter$ 





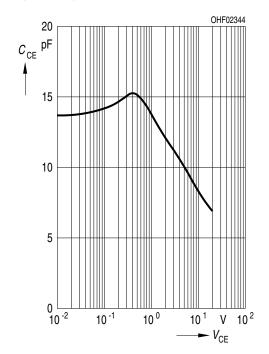
#### Dark Current 3), 4)

 $I_{CE0} = f(V_{CE}); E = 0$ 



# Collector-Emitter Capacitance <sup>3)</sup>

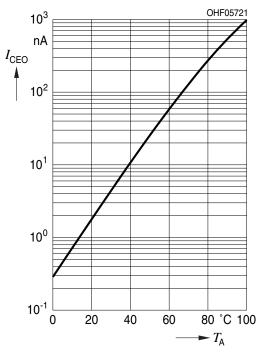
 $C_{CE} = f(V_{CE}); f = 1 \text{ MHz}; E = 0$ 





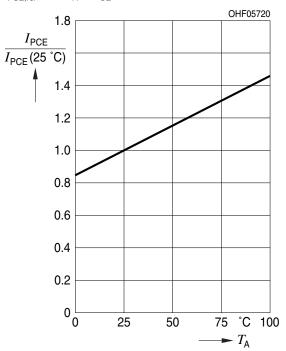
### Dark Current <sup>3)</sup>

 $\mathsf{I}_{_{\text{CE0}}}=\mathsf{f}\;(\mathsf{T}_{_{\text{A}}});\,\mathsf{V}_{_{\text{CE}}}=0$  V; E = 0 ; E\_\_e = 0 mW/cm²; 0

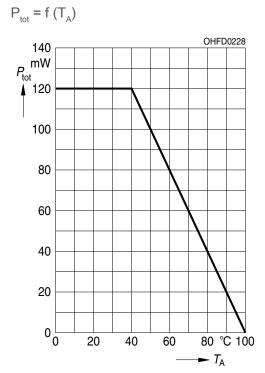


#### Photocurrent <sup>3)</sup>

 $I_{PCE,rel} = f(T_A); V_{CE} = 5 V$ 

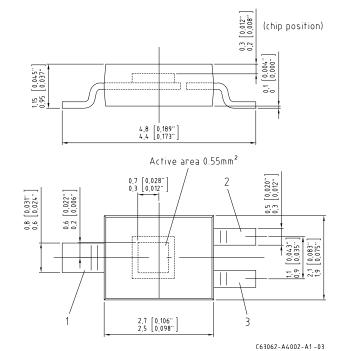


# **Power Consumption**





# Dimensional Drawing <sup>5)</sup>



### **Further Information:**

Approximate Weight:	12.0 mg
Package marking:	Collector

Pin	Description
1	collector
2	n.c.
3	emitter

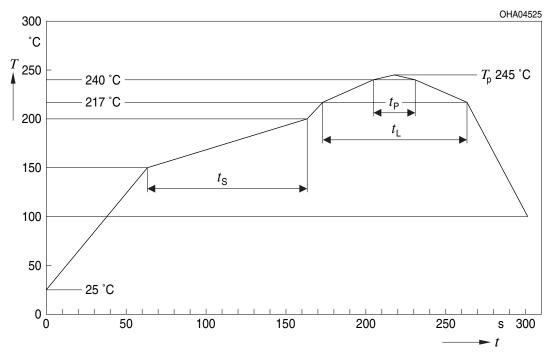


#### **Recommended Solder Pad**<sup>5)</sup> 1.9 1.9 1.8 17 1.8 5 φ -20 1.2 1.2 2.5 2.3 solder stencil foot print solder resist Component Location on Pad

E062.3010.216-01

### **Reflow Soldering Profile**

Product complies to MSL Level 4 acc. to JEDEC J-STD-020E



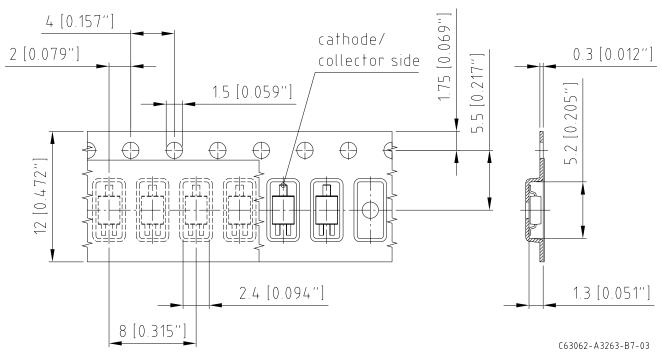


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Profile Feature	Symbol	Pb	-Free (SnAgCu) As	sembly	Unit
		Minimum	Recommendation	Maximum	
Ramp-up rate to preheat <sup>*)</sup> 25 °C to 150 °C			2	3	K/s
Time t <sub>s</sub> T <sub>Smin</sub> to T <sub>Smax</sub>	t <sub>s</sub>	60	100	120	S
Ramp-up rate to peak $^{*)}$ T $_{\rm Smax}$ to T $_{\rm P}$			2	3	K/s
Liquidus temperature	TL		217		°C
Time above liquidus temperature	t		80	100	S
Peak temperature	T <sub>P</sub>		245	260	°C
Time within 5 °C of the specified peak temperature $T_P$ - 5 K	t <sub>P</sub>	10	20	30	S
Ramp-down rate* T <sub>p</sub> to 100 °C			3	6	K/s
Time 25 °C to T <sub>P</sub>				480	S

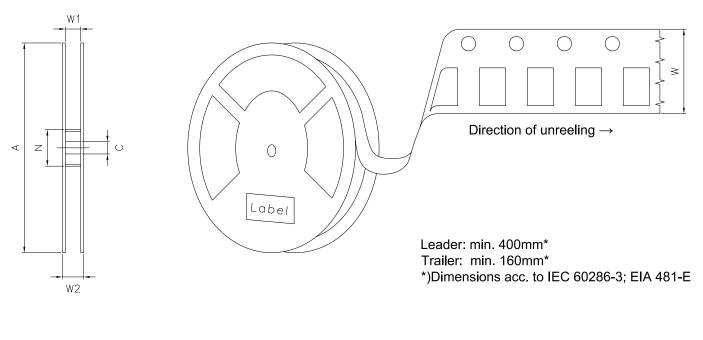
All temperatures refer to the center of the package, measured on the top of the component \* slope calculation DT/Dt: Dt max. 5 s; fulfillment for the whole T-range

### Taping <sup>5)</sup>





### Tape and Reel <sup>6)</sup>

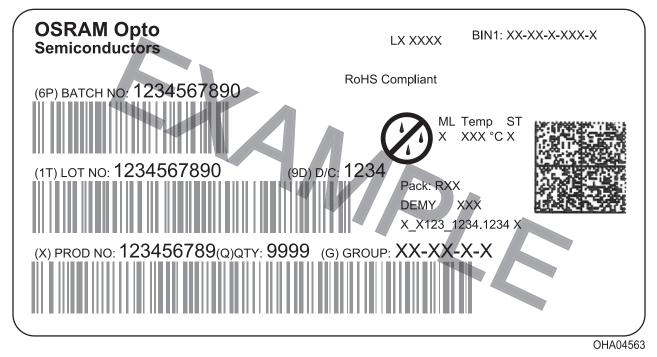


### **Reel Dimensions**

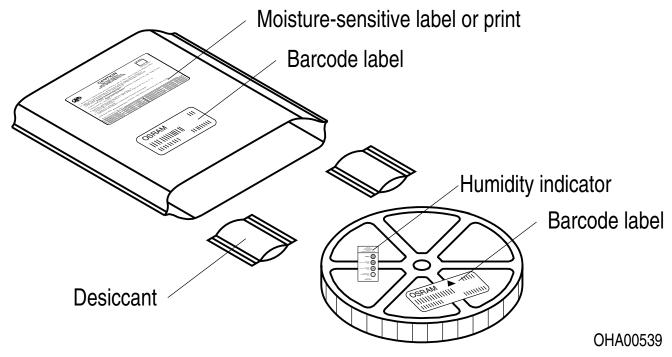
А	W	N <sub>min</sub>	W <sub>1</sub>	$W_{2\text{max}}$	Pieces per PU
180 mm	12 + 0.3 / - 0.1 mm	60 mm	12.4 + 2 mm	18.4 mm	2000



#### **Barcode-Product-Label (BPL)**



### Dry Packing Process and Materials <sup>5)</sup>



Moisture-sensitive product is packed in a dry bag containing desiccant and a humidity card according JEDEC-STD-033.



### **Notes**

The evaluation of eye safety occurs according to the standard IEC 62471:2006 (photo biological safety of lamps and lamp systems). Within the risk grouping system of this IEC standard, the device specified in this data sheet fall into the class **exempt group (exposure time 10000 s)**. Under real circumstances (for exposure time, conditions of the eye pupils, observation distance), it is assumed that no endangerment to the eye exists from these devices. As a matter of principle, however, it should be mentioned that intense light sources have a high secondary exposure potential due to their blinding effect. When looking at bright light sources (e.g. headlights), temporary reduction in visual acuity and afterimages can occur, leading to irritation, annoyance, visual impairment, and even accidents, depending on the situation.

Subcomponents of this device contain, in addition to other substances, metal filled materials including silver. Metal filled materials can be affected by environments that contain traces of aggressive substances. Therefore, we recommend that customers minimize device exposure to aggressive substances during storage, production, and use. Devices that showed visible discoloration when tested using the described tests above did show no performance deviations within failure limits during the stated test duration. Respective failure limits are described in the IEC60810.

For further application related information please visit www.osram-os.com/appnotes



### Disclaimer

#### Attention please!

The information describes the type of component and shall not be considered as assured characteristics. Terms of delivery and rights to change design reserved. Due to technical requirements components may contain dangerous substances.

For information on the types in question please contact our Sales Organization.

If printed or downloaded, please find the latest version on the OSRAM OS website.

#### Packing

Please use the recycling operators known to you. We can also help you – get in touch with your nearest sales office. By agreement we will take packing material back, if it is sorted. You must bear the costs of transport. For packing material that is returned to us unsorted or which we are not obliged to accept, we shall have to invoice you for any costs incurred.

#### Product and functional safety devices/applications or medical devices/applications

OSRAM OS components are not developed, constructed or tested for the application as safety relevant component or for the application in medical devices.

OSRAM OS products are not qualified at module and system level for such application.

In case buyer – or customer supplied by buyer – considers using OSRAM OS components in product safety devices/applications or medical devices/applications, buyer and/or customer has to inform the local sales partner of OSRAM OS immediately and OSRAM OS and buyer and /or customer will analyze and coordinate the customer-specific request between OSRAM OS and buyer and/or customer.



### Glossary

- <sup>1)</sup> **Photocurrent:** The photocurrent values are measured (by irradiating the devices with a homogenous light source and applying a voltage to the device) with a tolerance of ±11 %.
- <sup>2)</sup> **IPCEmin:** IPCEmin is the min. photocurrent of the specified group.
- <sup>3)</sup> **Typical Values:** Due to the special conditions of the manufacturing processes of semiconductor devices, the typical data or calculated correlations of technical parameters can only reflect statistical figures. These do not necessarily correspond to the actual parameters of each single product, which could differ from the typical data and calculated correlations or the typical characteristic line. If requested, e.g. because of technical improvements, these typ. data will be changed without any further notice.
- <sup>4)</sup> **Testing temperature:** TA = 25°C (unless otherwise specified)
- <sup>5)</sup> **Tolerance of Measure:** Unless otherwise noted in drawing, tolerances are specified with ±0.1 and dimensions are specified in mm.
- <sup>6)</sup> **Tape and Reel:** All dimensions and tolerances are specified acc. IEC 60286-3 and specified in mm.

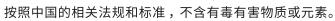


Revision History		
Version	Date	Change
1.4	2021-06-29	Schematic Transportation Box Dimensions of Transportation Box



SFH 3400

Published by OSRAM Opto Semiconductors GmbHEU RoHS and China RoHS compliant productLeibnizstraße 4, D-93055 Regensburg此产品符合欧盟 RoHS 指令的要求;





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